

RV5C040AP

Pch -20V -4.0A Small Signal MOSFET

Datasheet

V _{DSS}	-20V
R _{DS(on)} (Max.)	85mΩ
Ι _D	±4.0A
P _D	1.5W

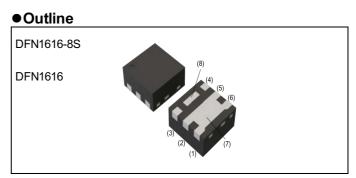
Features

- 1) Low on resistance.
- 2) -1.5V Drive.

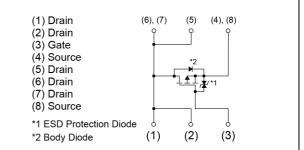
Application

Switching Load switch

- 3) Built-in G-S protection diode.
- 4) Small DFN package
- 5) Pb-free lead plating ; RoHS compliant



Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TCR1
	Marking	ZG

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

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Symbol	Value	Unit
V _{DSS}	-20	V
I _D *3	±4.0	А
I _{DP} *1	±16	А
V _{GSS}	0~-8	V
P _D *2	1.5	W
P _D *3	0.7	W
Tj	150	°C
T _{stg}	-55 to +150	°C
	$ V_{DSS} \\ I_{D}^{*3} \\ I_{DP}^{*1} \\ V_{GSS} \\ P_{D}^{*2} \\ P_{D}^{*3} \\ T_{j} \\ T $	V_{DSS} -20 I_D^{*3} ± 4.0 I_{DP}^{*1} ± 16 V_{GSS} $0 \sim -8$ P_D^{*2} 1.5 P_D^{*3} 0.7 T_j 150

•Thermal resistance

Deremeter	Symbol	Values			Unit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registerion, innotion, embient	R_{thJA}^{*2}	-	-	83.4	°C/W
Thermal resistance, junction - ambient	R_{thJA}^{*3}	-	-	179	°C/W

• Electrical characteristics ($T_a = 25^{\circ}C$)

Deremeter	Currence al	O a sa diti a sa a	Values			1.114	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -1mA	-20	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	-9.3	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = -20V, V _{GS} = 0V	-	-	-1.0	μΑ	
Gate - Source leakage current	I _{GSS}	V _{GS} = -8V, V _{DS} = 0V	-	-	-10	μA	
Gate threshold voltage	V _{GS(th)}	V _{DS} = -10V, I _D = -1mA	-0.3	-	-1.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	1.8	-	mV/°C	
		V _{GS} = -4.5V, I _D = -4.0A	-	60	85		
		V _{GS} = -2.5V, I _D = -1.2A	-	65	95		
Static drain - source	×3	V _{GS} = -1.8V, I _D = -1.2A	-	95	155		
on - state resistance	R _{DS(on)} *3	V _{GS} = -1.5V, I _D = -0.5A	-	130	260	mΩ	
		V _{GS} = -4.5V, I _D = -4.0A T _j = 125°C	-	80	-		
Gate resistance	R _G	f = 1MHz, open drain	-	10.6	-	Ω	
Forward Transfer $ Y_{fs} ^*$		V _{DS} = -5V, I _D = -4.0A	4	-	-	S	

*1 Pw \leq 10µs, Duty cycle \leq 1%

*2 Mounted on a Cu board (40×40mm×0.8mm)

- *3 Mounted on a ceramic board (30×30×0.8mm)
- *4 Pulsed



• Electrical characteristics ($T_a = 25^{\circ}C$)

Deremeter	Currence of	Conditions	Values			Linit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	2000	-		
Output capacitance	C _{oss}	V _{DS} = -10V	-	75	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	70	-		
Turn - on delay time	$t_{d(on)}^{*4}$	$V_{DD} \simeq -10V, V_{GS} = -4.5V$	-	10	-		
Rise time	t _r *4	I _D = -1.5A	-	30	-	20	
Turn - off delay time	t _{d(off)} *4	R _L ≃ 66.5Ω	-	120	-	ns	
Fall time	t _f *4	R _G = 10Ω	-	35	-		

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Deremeter	Sumbol	Conditions	Values			Unit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	UTIIL	
Total gate charge	Q_g^{*4}	V _{DD} ≃ -10V,	-	8.5	-		
Gate - Source charge	Q _{gs} *4	I _D = -2.5A,	-	3.5	-	nC	
Gate - Drain charge	${\sf Q}_{\sf gd}{}^{*4}$	V _{GS} = -4.5V	-	1.5	-		

•Body diode electrical characteristics (Source-Drain) ($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ _s	$T = 25^{\circ}$	-	-	-1.25	А
Pulse forward current	I_{SP}^{*1}	T _a = 25°C	-	-	-16	А
Forward voltage	V_{SD}^{*4}	V _{GS} = 0V, I _S = -2.5A	-	-	-1.2	V



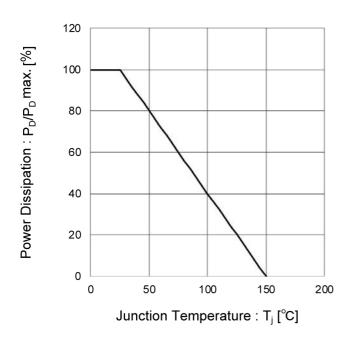


Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

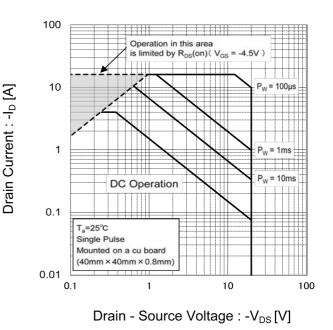
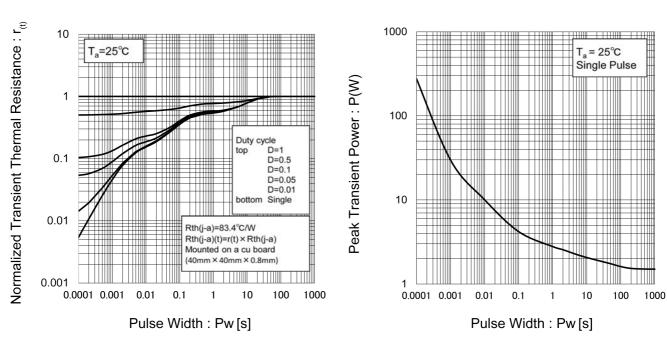


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power dissipation





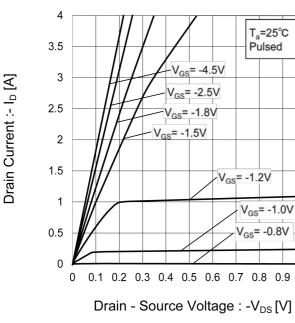


Fig.5 Typical Output Characteristics(I)

Fig.7 Breakdown Voltage vs. Junction Temperature

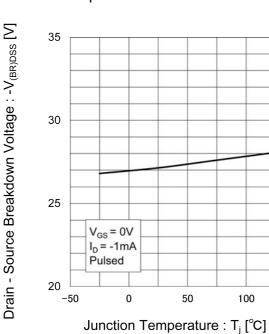


Fig.6 Typical Output Characteristics(II)

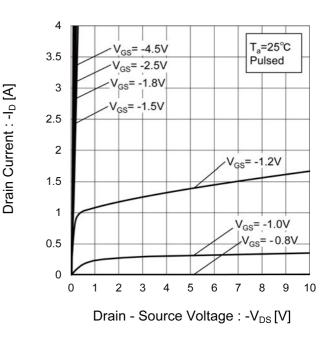
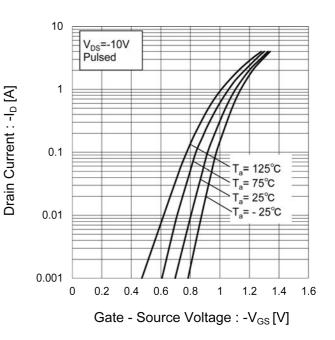


Fig.8 Typical Transfer Characteristics



150

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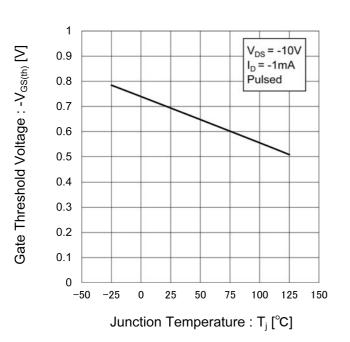
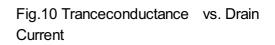


Fig.9 Gate Threshold Voltage vs. Junction Temperature



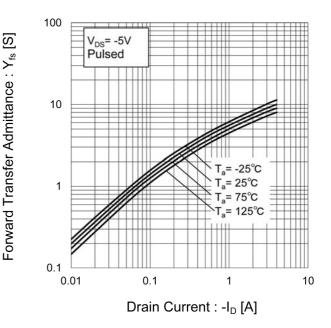


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

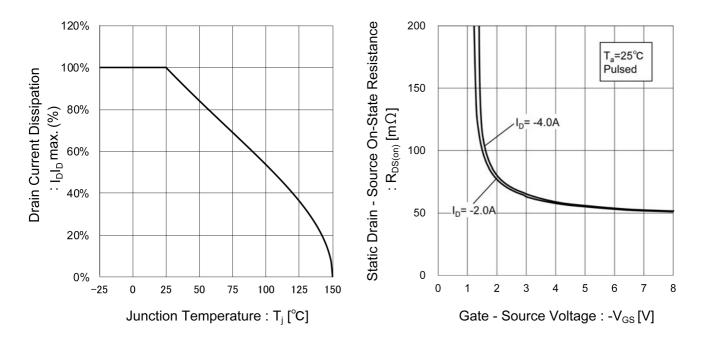




Fig.13 Static Drain - Source On - State

Resistance vs. Junction Temperature

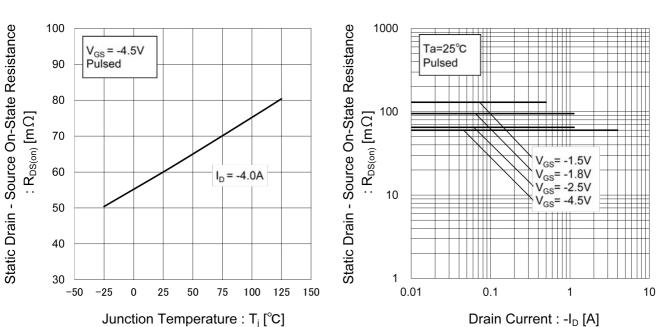


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II) Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

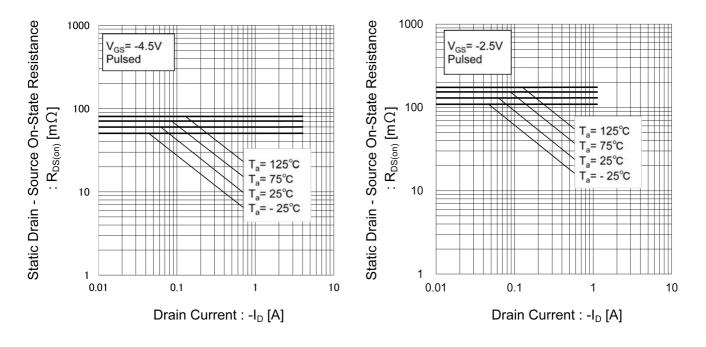




Fig.17 Static Drain - Source On - State

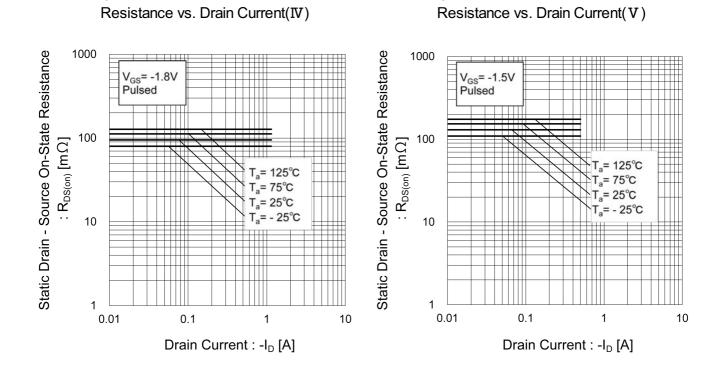
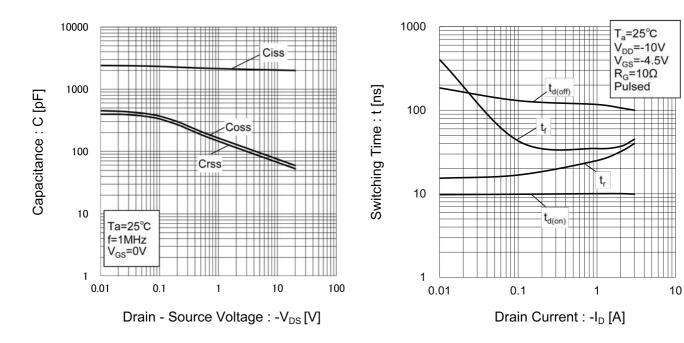


Fig.19 Typical Capacitance vs. Drain -Source Voltage

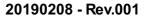
Fig.20 Switching Characteristics

Fig.18 Static Drain - Source On - State





ROHM



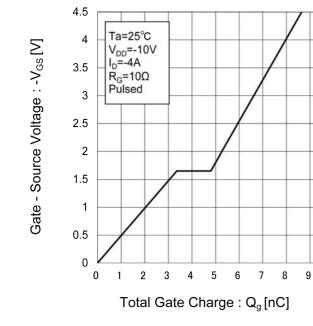
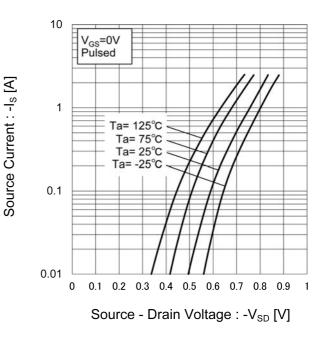


Fig.21 Dynamic Input Characteristics

Fig.22 Source Current vs. Source Drain Voltage





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Measurement circuits



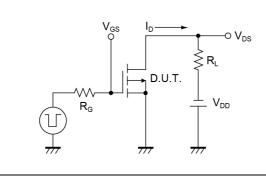


Fig.2-1 Gate Charge Measurement Circuit

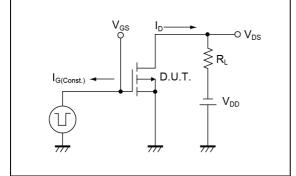
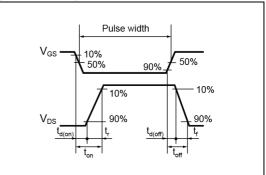
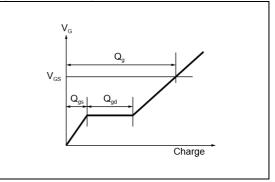


Fig.1-2 Switching Waveforms







Notice

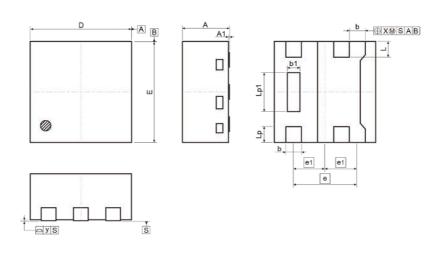
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.





Dimensions

DFN1616-8S DFN1616



DIM	MILIN	IETERS	INC	HES	
DIN	MIN	MAX	MIN	MAX	
А	0.70	0.80	0.027	0.032	
A1	0.00	0.05	0	0.002	
b	0.20	0.30	0.007	0.012	
b1	0.10	0.30	0.003	0.012	
D	1.50	1.70	0.059	0.067	
E	1.50	1.70	0.059	0.067	
е	1.	00	0.039		
e1	0.50		0.0)19	
Lp	0.20	0.30	0.007	0.011	
Lp1	0.52	0.72	0.02	0.028	
х		0.10	-	0.003	
У	- 100	0.10		0.003	

Dimension in mm/inches



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CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSIII	CLASSII	CLASSI

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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